

Features

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<10nA)
- Fast response time(<1ns)
- Bi-directional,single line protection
- IEC 61000-4-2 (ESD Air): 15kV
IEC 61000-4-2 (ESD Contact): 8kV

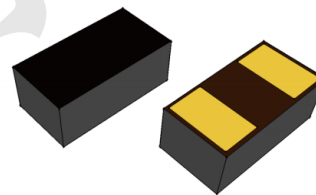
Mechanical Characteristics

- USB 3.0/3.1
- HDMI 1.3/1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Applications

- Smart Phone/Mobile Internet Device
- Laptop/Desktop Computer
- Bi-directional, single line protection
- Antennas (Cell Phones, GPS...)
- High Speed Ethernet
- USB 3.0 and USB 3.1

Dimensions and Pin Configuration



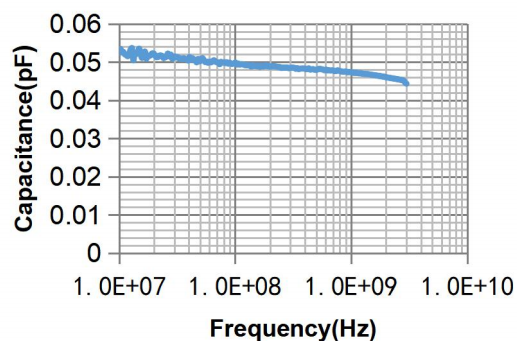
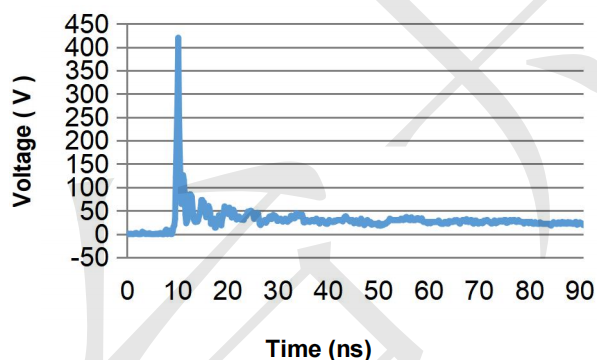
Absolute Maximum Ratings (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air)	VESD	±15	kV
ESD per IEC 61000-4-2 (Contact)		±8	
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	Tstg	-40 to +85	°C

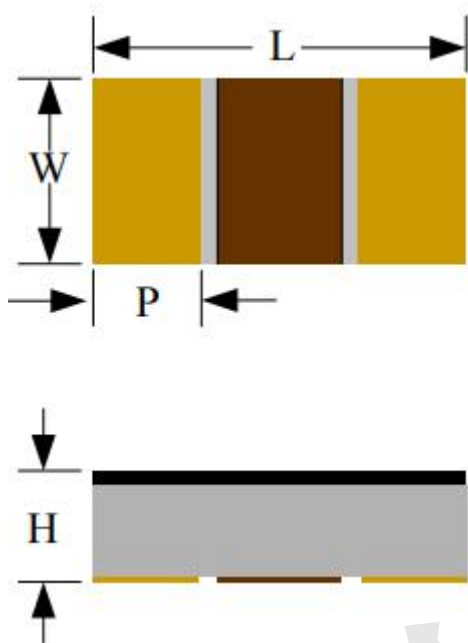
Electrical Characteristics (T_A=25 C unless otherwise noted)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Continuous Operating Voltage	V _{DC}			5	V	
Trigger Voltage	V _T		450		V	IEC61000-4-2 8kV contact discharge
Clamping Voltage	V _C		40		V	IEC61000-4-2 8kV contact discharge
Leakage Current	I _L			10	nA	DC 12 V shall be applied on component
Capacitance	C _J		0.05		pF	Measured at 10MHz

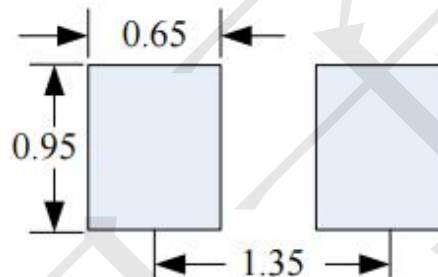
PROTECTION PRODUCTS Typical characteristics



Package Dimension



Recommended Solder Pad Footprint



***Sizes in mm**

Notes:

This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters	
	Min.	Max.
L	1.45	1.75
W	0.70	0.95
P	0.20	0.50
H	0.26	0.46